**To:**

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ROHM Co., Ltd
Transistor div.
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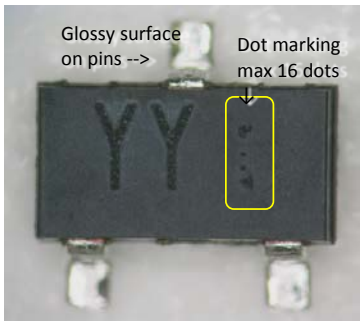
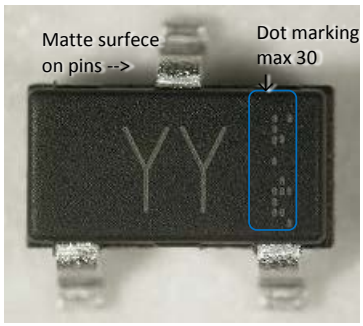
# Product Change Notification

**Content: Change for the purpose of better traceability, better solderability and environmental protection**

Application: TSMTpackage series (3, 5 and 6 pins)

| | | Current | After change (additional spec) |
|---|---|---|---|
| Contents of change | 1. Mold resin | Bromine-based flame retardant epoxy resin<br>(Flame retardant grade: UL94 V-0) | Halogen free flame retardant epoxy resin<br>(Flame retardant grade: UL94 V-0) |
| | | No change for products using Halogen free resin currently | |
| | 2. Solder composition | Sn-3Ag-0.5Cu (Dipped melted solder)<br>Solder surface: Glossy | Sn (Electro plating)<br>Solder surface: Matte |
| | 3. Making (Dot mark) | Discernible manufactured date with 16dots | Discernible complete production lot code with 30dots |
| | External appearance (Example) |  <br>(Current) |  <br>(After change) |
| | | note) Nothing changed for package dimension nor electrical characteristics<br>Nothing inferior for performance nor reliability to current products | |
| Reasons of change | 1. Shift to environmental friendly halogen-free resin<br>2. Improvement of solderability with pure-tin plating on pins<br>3. Perfect traceability with high density 30 dots marking on package | | |
| Termof change | Running change for the products of delivery from January/2015. | | |
| Attchment | Nothing | | |